

## CKC21C333MDGAC7210

KC-LINK Comm COG, Ceramic, 0.033 uF, 20%, 1000 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 2220



Click here for the 3D model.

Dimensions	
Chip Size	2220
L	5.9mm +/-0.4mm
W	5mm +/-0.4mm
Т	2.5mm +/-0.20mm
В	0.6mm +/-0.35mm

Packaging Specifications		
Packaging	T&R, 330mm, Plastic Tape	
Packaging Quantity	2000	

General Information	
Series	KC-LINK Comm COG
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	320 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.033 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	20%
Voltage DC	1000 VDC
Dielectric Withstanding Voltage	1200 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	30.303 GOhms

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